

Title (en)

TITANIUM COPPER, METHOD FOR PRODUCING TITANIUM COPPER AND ELECTRONIC COMPONENT

Title (de)

TITANKUPFERLEGIERUNG, VERFAHREN ZUR DEREN HERSTELLUNG SOWIE ELEKTRONISCHES BAUTEIL

Title (fr)

ALLIAGE DE TITANE ET CUIVRE, PROCÉDÉ DE SON FABRICATION ET COMPOSANT ÉLECTRONIQUE

Publication

**EP 3643799 A1 20200429 (EN)**

Application

**EP 19202704 A 20191011**

Priority

JP 2018198622 A 20181022

Abstract (en)

Provided is titanium copper having improved stress relaxation resistance, a method for producing the titanium copper, and an electronic component using the titanium copper. A titanium copper, the titanium copper containing from 2.0 to 4.5% by mass of Ti, and a total amount of from 0 to 0.5% by mass of at least one selected from the group consisting of Fe, Co, Ni, Cr, Zn, Zr, P, B, Mo, V, Nb, Mn, Mg, and Si as a third element, the balance being copper and inevitable impurities, wherein an area ratio of crystal grains with a GOS (Grain Orientation Spread) of from 2 to 6° when an orientation difference of 5° or more is regarded as a crystal grain boundary in crystal orientation analysis in an EBSD measurement on a rolled surface is from 60 to 90%, and an area ratio of crystal grains with a Schmidt factor of 0.35 or less is from 5 to 20%.

IPC 8 full level

**C22C 9/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP)

**C22C 9/00** (2013.01); **C22F 1/08** (2013.01)

Citation (applicant)

- JP 2014185370 A 20141002 - DOWA METALTECH KK
- JP 2010126777 A 20100610 - DOWA METALTECH KK
- JP 2008308734 A 20081225 - DOWA METALTECH KK
- JP H07258803 A 19951009 - NIKKO KINZOKU KK

Citation (search report)

- [A] US 2016062212 A1 20160303 - NAGANO MASAYUKI [JP]
- [A] EP 2194149 A1 20100609 - DOWA METALTECH CO LTD [JP] & JP 2010126777 A 20100610 - DOWA METALTECH KK

Cited by

CN111733372A; CN114152638A; CN116024444A

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 3643799 A1 20200429**; **EP 3643799 B1 20201209**; JP 2020066756 A 20200430; JP 6736630 B2 20200805; RU 2019133232 A 20210421

DOCDB simple family (application)

**EP 19202704 A 20191011**; JP 2018198622 A 20181022; RU 2019133232 A 20191021